



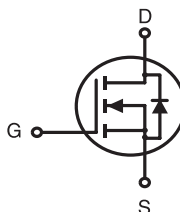
N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	R _{DS(ON)} (mΩ) Typ
100V	26A	49 @ V _{GS} =10V

FEATURES

- Super high dense cell design for low R_{DS(ON)}.
- Rugged and reliable.
- TO-263 Package.



ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Symbol	Parameter		Limit	Units
V _{DS}	Drain-Source Voltage		100	V
V _{GS}	Gate-Source Voltage		±20	V
I _D	Drain Current-Continuous	T _C =25°C	26	A
		T _C =70°C	21.8	A
I _{DM}	-Pulsed ^a		76	A
E _{AS}	Single Pulse Avalanche Energy ^c		36	mJ
P _D	Maximum Power Dissipation	T _C =25°C	75	W
		T _C =70°C	52.5	W
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 175	°C

THERMAL CHARACTERISTICS

R _{θJC}	Thermal Resistance, Junction-to-Case	2	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

STB31L01

Ver 1.1

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	2.0	3	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =13A		49	60	m ohm
g _{FS}	Forward Transconductance	V _{DS} =10V , I _D =13A		22		S
DYNAMIC CHARACTERISTICS ^b						
C _{ISS}	Input Capacitance	V _{DS} =25V,V _{GS} =0V f=1.0MHz		1460		pF
C _{OSS}	Output Capacitance			88		pF
C _{RSS}	Reverse Transfer Capacitance			75		pF
SWITCHING CHARACTERISTICS ^b						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =50V I _D =1A V _{GS} =10V R _{GEN} = 6 ohm		25		ns
t _r	Rise Time			23		ns
t _{D(OFF)}	Turn-Off Delay Time			66		ns
t _f	Fall Time			14		ns
Q _g	Total Gate Charge	V _{DS} =50V,I _D =13A,V _{GS} =10V		26		nC
Q _{gs}	Gate-Source Charge	V _{DS} =50V,I _D =13A, V _{GS} =10V		2.6		nC
Q _{gd}	Gate-Drain Charge			9.3		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V,I _S =4A		0.79	1.3	V
Notes						
a.Pulse Test:Pulse Width ≤ 300us, Duty Cycle ≤ 2%.						
b.Guaranteed by design, not subject to production testing.						
c.Starting T _J =25°C,L=0.5mH,V _{DD} =50V.(See Figure13)						

Sep,20,2012

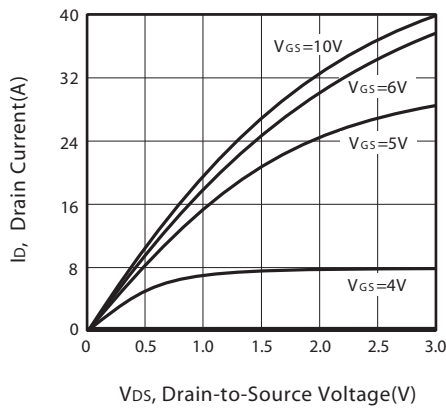


Figure 1. Output Characteristics

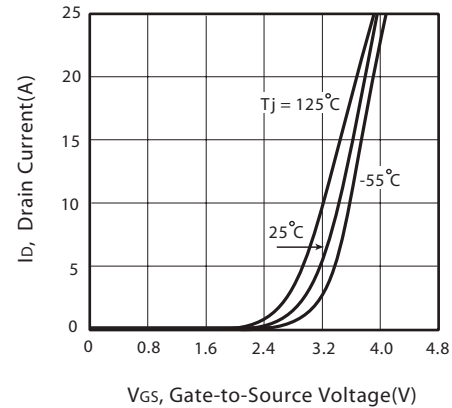


Figure 2. Transfer Characteristics

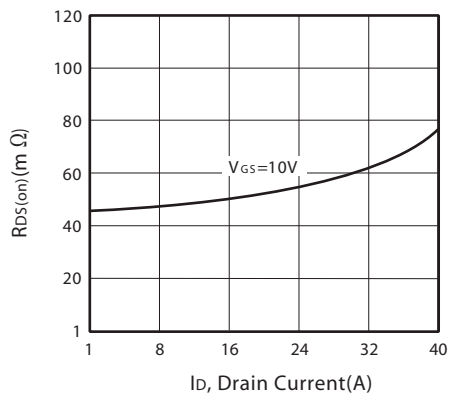


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

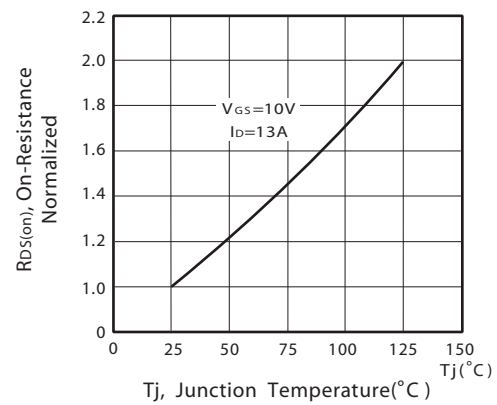


Figure 4. On-Resistance Variation with Drain Current and Temperature

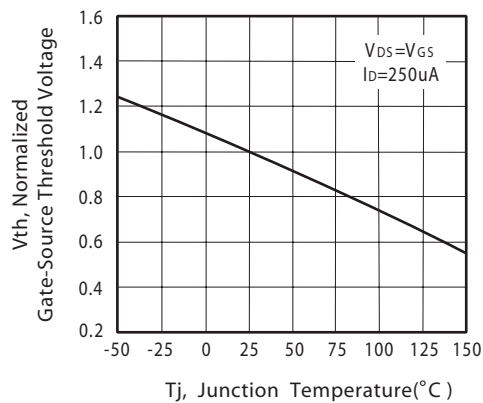


Figure 5. Gate Threshold Variation with Temperature

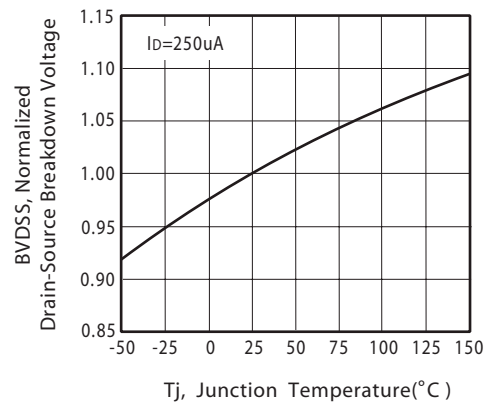


Figure 6. Breakdown Voltage Variation with Temperature

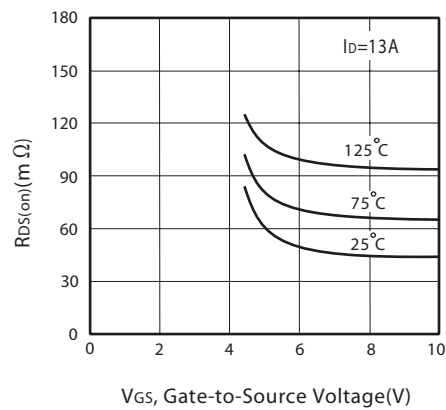


Figure 7. On-Resistance vs. Gate-Source Voltage

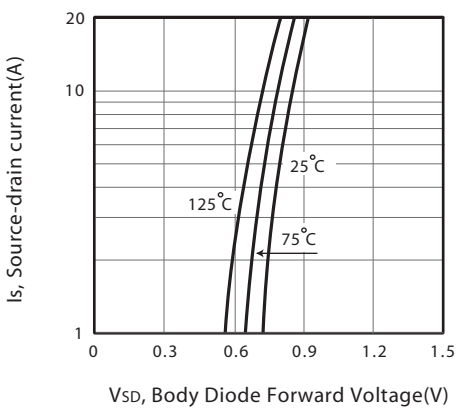


Figure 8. Body Diode Forward Voltage Variation with Source Current

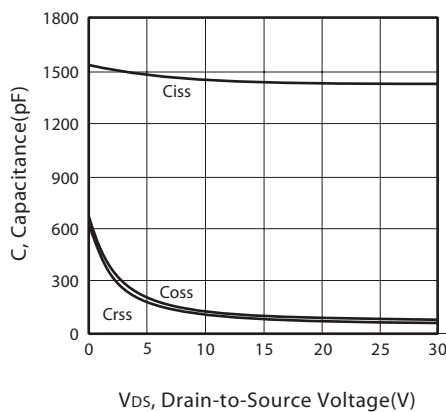


Figure 9. Capacitance

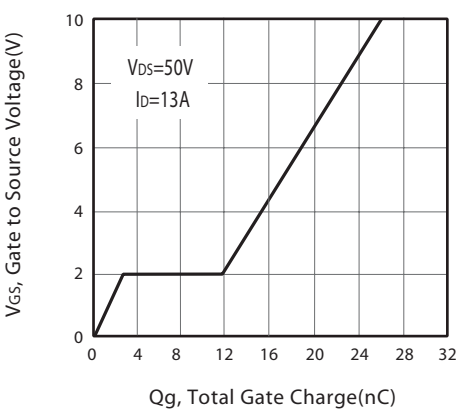


Figure 10. Gate Charge

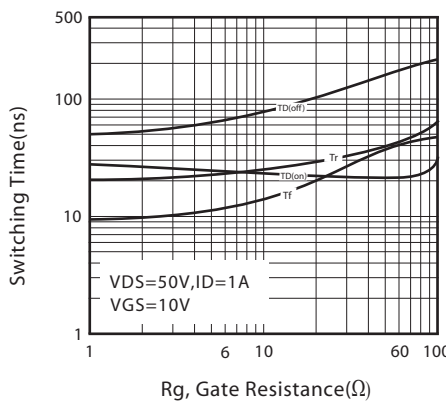


Figure 11. switching characteristics

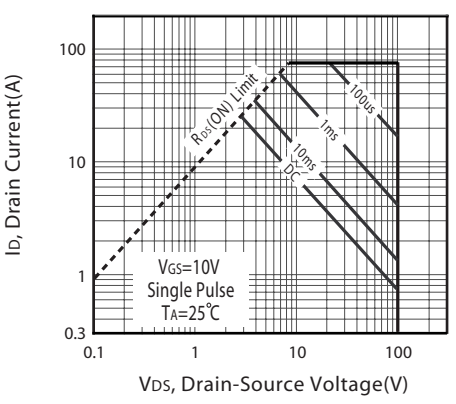
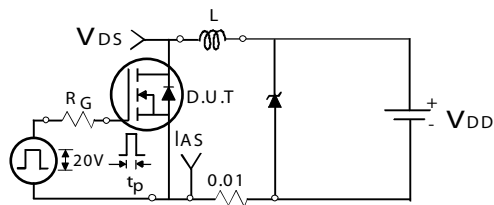
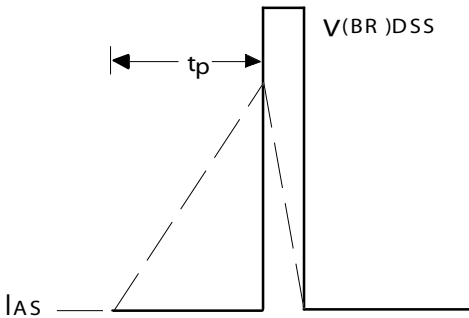


Figure 12. Maximum Safe Operating Area



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

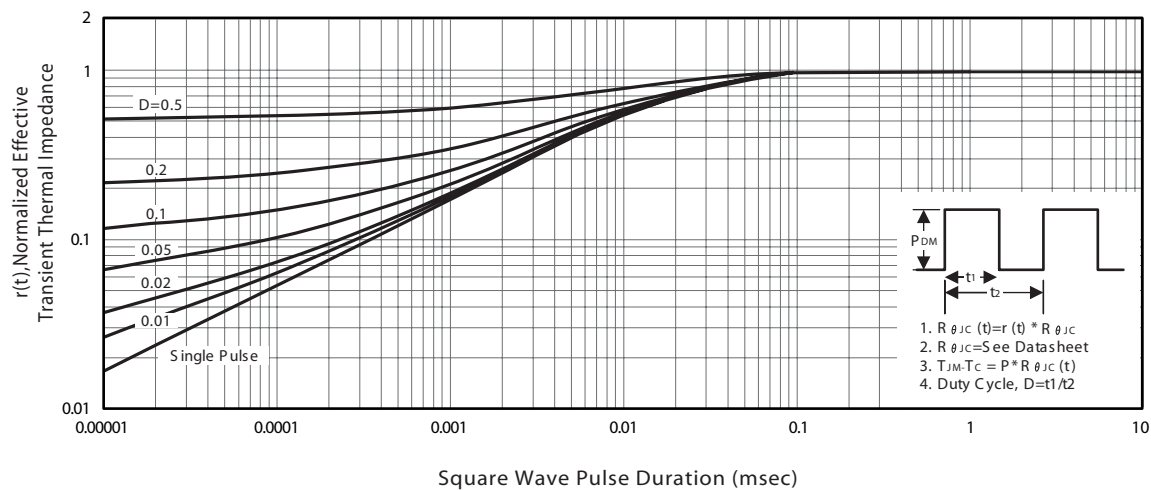
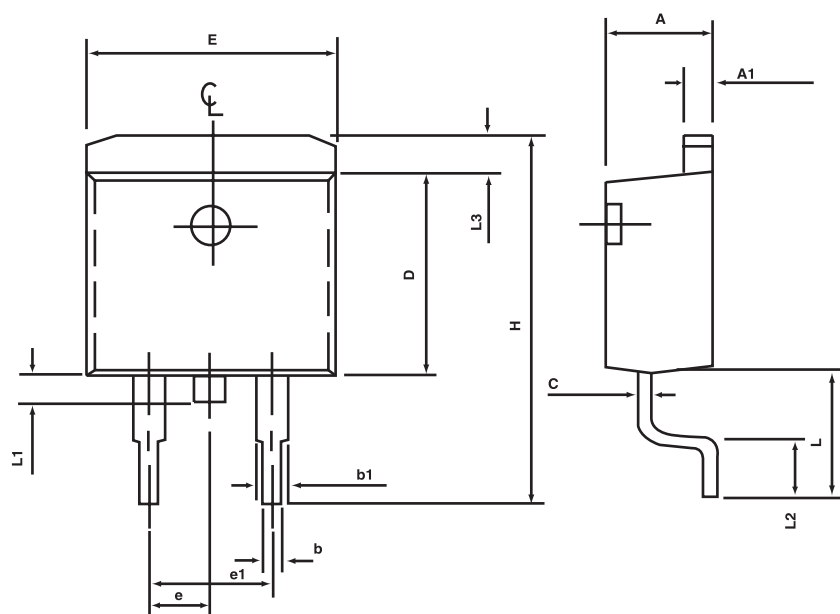


Figure 14. Normalized Thermal Transient Impedance Curve

PACKAGE OUTLINE DIMENSIONS

TO-263AB



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.70	0.169	0.185
A1	1.22	1.32	0.048	0.055
b	0.69	0.94	0.027	0.037
b1	1.22	1.40	0.048	0.055
C	0.36	0.56	0.014	0.022
D	8.64	9.652	0.340	0.380
E	9.70	10.54	0.382	0.415
e	2.29	2.79	0.090	0.110
e1	4.83	5.33	0.190	0.210
H	14.60	15.78	0.575	0.625
L	4.70	5.84	0.185	0.230
L1	1.20	1.778	0.047	0.070
L2	2.24	2.84	0.088	0.111
L3	1.40 MAX		0.055 MAX	

TO-263AB Tube

